

UNISONIC TECHNOLOGIES CO., LTD

8NM70A Power MOSFET

8A, 700V N-CHANNEL **POWER MOSFET**

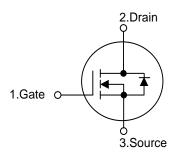
DESCRIPTION

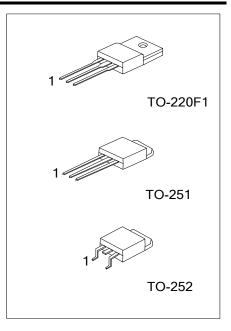
The UTC 8NM70A is a high voltage super junction MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in switching power supplies and adaptors.

FEATURES

- * $R_{DS(ON)} \le 0.7 \Omega$ @ $V_{GS}=10V$, $I_D=1.0A$
- * Fast Switching Capability
- * Improved dv/dt Capability, High Ruggedness

SYMBOL

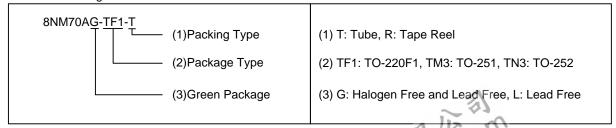




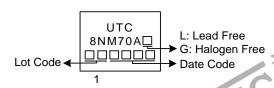
ORDERING INFORMATION

Ordering Number		Daakaas	Pin Assignment			Do akin n	
Lead Free	Halogen Free	Package	1	2	3	Packing	
8NM70AL-TF1-T	8NM70AG-TF1-T	TO-220F1	G	D	S	Tube	
8NM70AL-TM3-T	8NM70AG-TM3-T	TO-251	G	D	S	Tube	
8NM70AL-TN3-R	8NM70AG-TN3-R	TO-252	G	D	S	Tape Reel	

Pin Assignment: G: Gate D: Drain S: Source Note:



MARKING



www.unisonic.com.tw 1 of 6 QW-R205-341.B

■ **ABSOLUTE MAXIMUM RATINGS** (T_C = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	700	V
Gate-Source Voltage		V_{GSS}	±30	V
Drain Current	Continuous	l _D	8	Α
	Pulsed (Note 2)	I_{DM}	32	Α
Avalanche Energy Single Pulsed (Note 3)		E _{AS}	110	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	5.0	V/ns
Power Dissipation	TO-220F1	5	28	W
	TO-251/TO-252	P_D	54	W
Junction Temperature		TJ	+150	°C
Storage Temperature		T_{STG}	-55 ~ + 150	ô

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L=60mH, I_{AS} =1.92A, V_{DD} =50V, R_{G} =25 Ω , Starting T_{J} = 25°C
- 4. $I_{SD} \le 8.0A$, di/dt $\le 200A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25$ °C

■ THERMAL DATA

PARAMETER		SYMBOL RATING		UNIT
Junction to Ambient	TO-220F1	0	62.5	°C/W
	TO-251/TO-252	θ_{JA}	110	°C/W
Junction to Case	TO-220F1	0	4.46	°C/W
	TO-251/TO-252	θ_{JC}	2.31 (Note)	°C/W

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.



ELECTRICAL CHARACTERISTICS (T_J =25°C, unless otherwise specified)

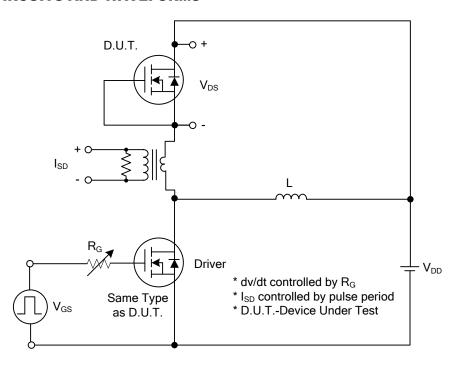
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT		
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage	BV _{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	700			V		
Drain-Source Leakage Current	I _{DSS}	$V_{DS} = 700V, V_{GS} = 0V$			10	μΑ		
Forward	I _{GSS}	$V_{GS} = 30V, V_{DS} = 0V$			100	nA		
Gate- Source Leakage Current Reverse		$V_{GS} = -30V, V_{DS} = 0V$			-100	nΑ		
ON CHARACTERISTICS								
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	2.5		4.5	V		
Static Drain-Source On-State Resistance	R _{DS(ON)}	$V_{GS} = 10V, I_D = 1.0A$			0.7	Ω		
DYNAMIC CHARACTERISTICS								
Input Capacitance	C _{ISS}			451		pF		
Output Capacitance	Coss	V _{DS} =25V, V _{GS} =0V, f=1.0 MHz		260		pF		
Reverse Transfer Capacitance	C _{RSS}			25		pF		
Gate Resistance	R_G	V _{GS} =0V, f=1.0MHz		2.2		Ω		
SWITCHING PARAMETERS								
Total Gate Charge (Note 1)	Q_G	V _{DS} =50V, V _{GS} =10V, I _D =1.3A,		17.8		nC		
Gate to Source Charge	Q _{GS}	I _G =100μA (Note 1, 2)		4.6		nC		
Gate to Drain Charge	Q_{GD}	IG=100μA (Note 1, 2)		10.4		nC		
Turn-on Delay Time (Note 1)	t _{D(ON)}			43		ns		
Rise Time	t _R	$V_{DD}=30V, V_{GS}=10V, I_{D}=0.5A,$		78		ns		
Turn-off Delay Time	t _{D(OFF)}	R _G =25Ω (Note 1, 2)		174		ns		
Fall-Time	t _F			60		ns		
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS								
Maximum Body-Diode Pulsed Current	Is				8	Α		
Drain-Source Diode Forward Voltage (Note 1)	I _{SM}				32	Α		
Maximum Body-Diode Continuous Current	V _{SD}	I _S =8.0A, V _{GS} =0V			1.4	V		
Reverse Recovery Time (Note 1)	t _{rr}	I _S =8.0A, V _{GS} =0V		328		ns		
Reverse Recovery Charge	Q_{rr}	dI _F /dt=100A/μs		3.94		μC		

Notes: 1. Pulse Test: Pulse width ≤ 300µs, Duty cycle ≤2%.

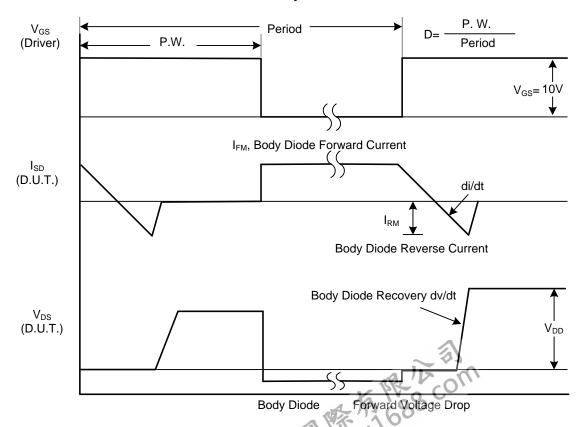
2. Essentially independent of operating temperature.



■ TEST CIRCUITS AND WAVEFORMS

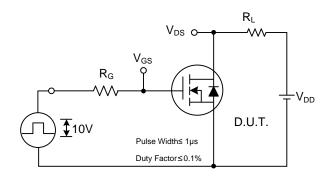


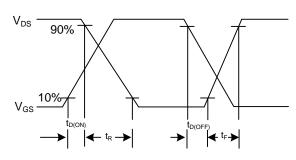
Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms

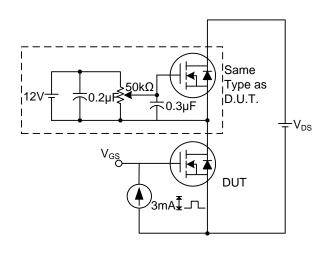
TEST CIRCUITS AND WAVEFORMS

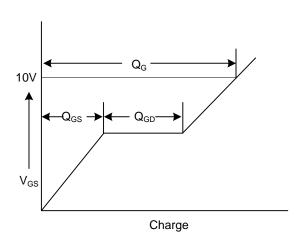




Switching Test Circuit

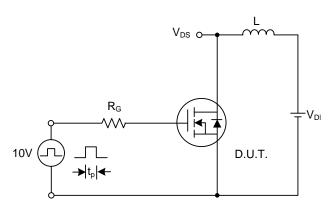
Switching Waveforms

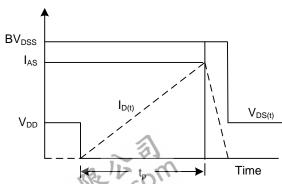




Gate Charge Test Circuit

Gate Charge Waveform





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